

**IN THE CLAIMS**

This is a complete and current listing of the claims, marked with status identifiers in parentheses. The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Currently Amended) An electronic power module, ~~in particular for an electronic motor controller for soft starting motors,~~ having comprising:

~~—~~ — a first and a second cooling device ~~(7 to 12);~~ and

~~—~~ — a semiconductor device, ~~(1) which is arranged between the first and the second cooling device (7 to 12);~~ ;

~~characterized in that~~

~~—~~ — an elastic annular element, ~~(6) is arranged around the semiconductor device (1), with the a space within the elastic annular element (6) being encapsulated and being partially bounded by the first and second cooling devices (7 to 12), and the semiconductor device (1) being located in said the space.~~

2. (Currently Amended) The electronic power module as claimed in claim 1, wherein with the first and second cooling devices ~~(7 to 12)~~ each ~~having~~ include at least one heat sink ~~(9 to 12).~~

3. (Currently Amended) The electronic power module as claimed in claim 1 ~~or 2,~~ with wherein at least one of the first and/or second cooling devices or device (7 to 12) each having include a metal rail ~~(7, 8)~~ for directly transporting heat away from the semiconductor device ~~(1)~~ and for making electrical contact with the semiconductor device ~~(1).~~

4. (Currently Amended) The electronic power module as claimed in claim 3, ~~with~~ wherein the respective metal rail ~~(7, 8)~~ and the at least one heat sink ~~(9 to 12)~~ beingare integral.

5. (Currently Amended) The electronic power module as claimed in claim 3 ~~or 4~~, ~~with~~ wherein the respective metal rail ~~(7, 8)~~ and the at least one heat sink ~~(9 to 12)~~ beingare composed of at least one of copper and ~~or~~ aluminum.

6. (Currently Amended) The electronic power module as claimed in ~~one of the preceding claims~~ claim 1, ~~with~~ wherein the semiconductor device ~~(1)~~ havingincludes two semiconductor elements ~~(TH1 to TH4)~~ electrically connected back-to-back in parallel.

7. (Currently Amended) The electronic power module as claimed in claim 6, ~~with~~ wherein the semiconductor elements ~~(TH1 to TH4)~~ beingare in the form of semiconductor cells ~~(2)~~ without a housing.

8. (Currently Amended) The electronic power module as claimed in ~~one of the preceding claims~~, with claim 1, wherein the annular element ~~(6)~~ beingis composed of rubber.

9. (Currently Amended) The electronic power module as claimed in ~~one of the preceding claims~~, with claim 1, wherein the annular element ~~(6)~~ beingis of a size which is substantially constant in the axial direction, so that a prespecified air gap and creepage distance are ensured between the first and second cooling devices ~~(7 to 12)~~.

10. (Currently Amended) The electronic power module as claimed in ~~one of the preceding claims~~, with claim 1, wherein

the annular element ~~(6)~~ having includes an opening or cutout ~~(17)~~ through which at least one of lines (3, 5) for triggering a thyristor are passed and ~~or through which~~ an encapsulation compound ~~(16)~~ is introduced.

11. (Currently Amended) A method for producing an electronic power module, ~~in particular for an electronic motor controller for soft-starting motors, by comprising:~~

\_\_\_\_\_—arranging a semiconductor device ~~(1)~~ between a first and a second cooling device; ~~(7 to 12),~~  
~~characterized by~~

\_\_\_\_\_—arranging an elastic annular element ~~(6)~~ around the semiconductor device ~~(1)~~, with a space being produced within the annular element ~~(6)~~, ~~which the space is being~~ partially bounded by the first and second cooling devices ~~(7 to 12)~~ and ~~in which~~ the semiconductor device ~~(1)~~ is being located in the space; and

\_\_\_\_\_—encapsulating the space with an encapsulation compound ~~(16)~~.

12. (Currently Amended) The method as claimed in claim 11, ~~with wherein~~ the annular element ~~(6)~~, before encapsulation, ~~creating creates~~ a space between the two cooling devices ~~(7 to 12)~~ in such a way that at least one of a prespecified air gap ~~or and~~ creepage distance is ensured between the first and the second cooling device ~~(7 to 12)~~.

13. (New) The electronic power module of claim 1, wherein the electronic power module is for an electronic motor controller for a soft-starting motor.

14. (New) The electronic power module as claimed in claim 2, wherein at least one of the first and second cooling device

include a metal rail for directly transporting heat away from the semiconductor device and for making electrical contact with the semiconductor device.

15. (New) The electronic power module as claimed in claim 4, wherein the respective metal rail and the at least one heat sink are composed of at least one of copper and aluminum.

16. (New) The method of claim 11, wherein the electronic power module is for an electronic motor controller for a soft-starting motor.